

1

2

3

4

A

A

B

B

C

C

D

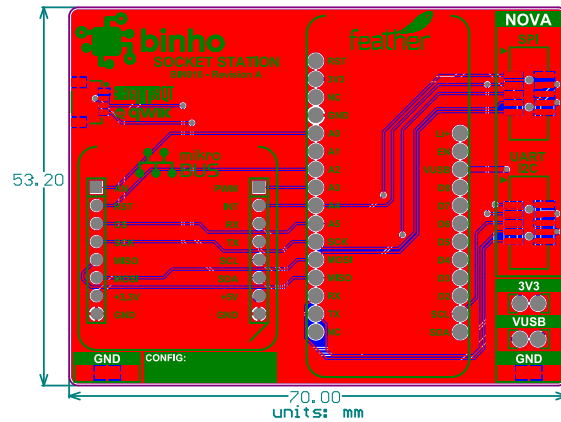
D

Layer Stack Up

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric1	FR-4	1.510mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Component Placement

(mirrored)



Assembly Notes

- [1] Material Type: FR-4 or equivalent
- [2] Minimum Hole Size: 0.4mm
- [3] Minimum Trace/Spacing: 6 mil / 6 mil
- [4] Surface Finish: ENIG
- [5] Soldermask Color: Black
- [6] Silkscreen Color: White
- [7] Finished PCB Thickness: 1.6mm nominal
- [8] Controlled Impedance: No
- [9] Must be RoHS Compliant
- [10] 100% Electrical Test

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DATE:
4/6/2020



PRODUCT:
Socket Station

REV:
A

1

2

3

4